



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

The 2012 IEEE-CPMT / IMAPS Advanced Technology Workshop on Optoelectronic Packaging and Assembly



Advance Announcement

The Institute of Electrical and Electronics Engineers - Components, Packaging and Manufacturing Technology Society (IEEE-CPMT) and the International Microelectronics and Packaging Society (IMAPS) jointly announce the 2012 Advanced Technology Workshop on Opto-electronic Packaging and Assembly. This workshop will feature an ITRS Assembly and Packaging Roadmap working session as well.

Dates: **September 6 & 7, 2012**

Location: **Embassy Suites, 3100 East Frontera Street, Anaheim, CA 92806**

**Thursday, September 6, 2012
8:00 am – 5:00 pm**

Optoelectronic Packaging & Assembly

Invited technical experts will be presenting on the advances and trends in the Optoelectronic Packaging and Assembly Technology areas for applications such as **Optical Interconnects & Semiconductor Photonics, Optical Transceivers & Networks, High Brightness LED and CMOS Image Sensors.**

Featured Speakers:

Keynote Address: **Prof. Ricky Lee, President, IEEE CPMT Society**

Dr. Mehdi Asghari, Kotura

Dr. Daniel Van Blerkom, Forza Silicon

Ron Bonne, Philips Lumileds

Dr. Jack Cunningham, Oracle Labs

Dr. Peter De Dobbelaere, Luxtera

Dr. Ali Ghiasi, Broadcom

Dr. Radha Nagarajan, Infinera

Dr. Adit Narasimha, Molex

Prof. George Papen, UCSD

Dr. Mark Verdiell, Samtec

and more.

**Friday, September 7, 2012
8:00 am – 12:00 pm**



ITRS Assembly & Packaging Roadmap Working Session

The International Technology Roadmap for Semiconductors (ITRS) Organization will hold an assembly and packaging roadmap working session for the workshop participants, with a presentation on the ITRS working process and an interactive discussion about their optoelectronic packaging activities.

Platinum Sponsor



For Sponsorship & Vendor Exhibition inquiries, please contact:

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